

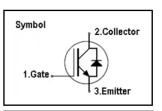
IGBT

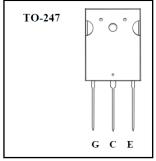
Features

- 600V,40A
- $V_{CE(sat)(typ.)}$ =2.0V@ V_{GE} =15V, I_{C} =40A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as SMPS, general inverter and other switching applications.





Absolute Maximum Ratings(Tc=25℃ unless otherwise noted)

Symbol	Parameter	Value	Units	
Vces	Collector-Emitter Voltage	600	V	
V _{GES}	s Gate-Emitter Voltage <u>+</u> 30			
,	Continuous Collector Current (Tc=25 °C)	80	Α	
Ic	Continuous Collector Current (T _C =100°C)	40	Α	
Ісм	Pulsed Collector Current (Note 1) 90		А	
l _F	Diode Continuous Forward Current (T _C =100 °C) 40		А	
I _{FM}	Diode Maximum Forward Current (Note 1) 90		А	
t _{sc}	Short Circuit Withstand Time 10		us	
Б	Maximum Power Dissipation (Tc=25 ℃)	205	W	
P _D	Maximum Power Dissipation (Tc=100°C)	82	W	
TJ	Operating Junction Temperature Range -55 to +150		$^{\circ}$	
T _{STG}	Storage Temperature Range	-55 to +150	$^{\circ}$	

Thermal Characteristics

Symbol	Parameter	Max.	Units
R _{th j-c}	Thermal Resistance, Junction to case for IGBT	0.61	°C/ W
R _{th j-c}	Thermal Resistance, Junction to case for Diode	1.1	°C/ W
R _{th j-a}	Thermal Resistance, Junction to Ambient	40	°C/ W



$\underline{\textbf{Electrical Characteristics}} \text{ (Tc=25\,^{\circ}\text{C} unless otherwise noted)}$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 600V, V _{GE} = 0V	-	-	100	uA
	Gate Leakage Current, Forward	V_{GE} =30V, V_{CE} = 0V	-	-	100	nA
I _{GES}	Gate Leakage Current, Reverse	V_{GE} = -30V, V_{CE} = 0V	-	-	100	nA
$V_{\text{GE(th)}}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_{C} = 250uA$	4.5	-	6.5	V
$V_{\text{CE(sat)}}$	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 40A	-	2.0	2.55	V
Qg	Total Gate Charge	Vcc=480V	-	75.1		nC
Q _{ge}	Gate-Emitter Charge	V _{GE} =460V V _{GE} =15V	-	25.4		nC
Q _{gc}	Gate-Collector Charge	Ic=40A	-	44.9		nC
t d(on)	Turn-on Delay Time		-	62	-	ns
t _r	Turn-on Rise Time	Vcc=400V	-	203	-	ns
t d(off)	Turn-off Delay Time	V _{GE} =15V	-	266	-	ns
t f	Turn-off Fall Time	I _C =40A R _G =15Ω	-	118	-	ns
Eon	Turn-on Switching Loss	Inductive Load	-	3.16	-	mJ
Eoff	Turn-off Switching Loss		-	1.05	-	mJ
Ets	Total Switching Loss		-	4.21	-	mJ
Cies	Input Capacitance	V _{CE} =25V V _{GE} =0V	-	1855	-	pF
C _{oes}	Output Capacitance		-	150.5	-	pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz	-	19.9	-	pF

Electrical Characteristics of Diode (Tc=25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _F	Diode Forward Voltage	I _F =40A	-	1.35	2.0	V
trr	Diode Reverse Recovery Time	V _{CE} = 400V		350		ns
Irr	Diode peak Reverse Recovery Current	I _F = 40A		6.56		Α
Qrr	Diode Reverse Recovery Charge	RG=15Ω	-	0.7		uC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



Typical Performance Characteristics

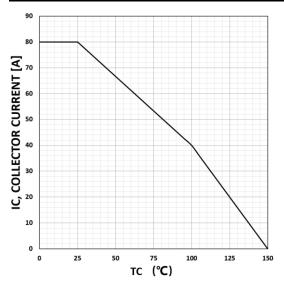


Figure 1. Maximum DC collector current VS. case temperature

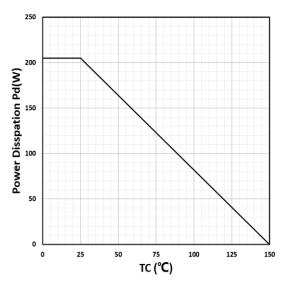


Figure 2. Power dissipation VS. case temperature

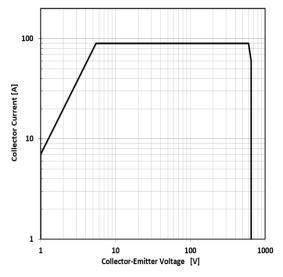


Figure 3. Reverse bias SOA, Tj=125℃,Vge=15V

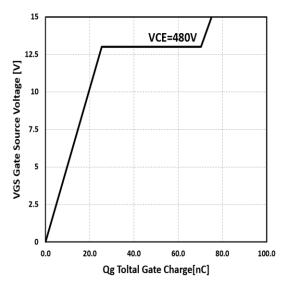


Figure4:Typical gate charge VS. VGE,IC=40A





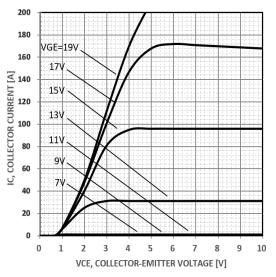


Figure 5. Typical output characteristics tp=300us $\,$ Tc=25 $\,$ °C

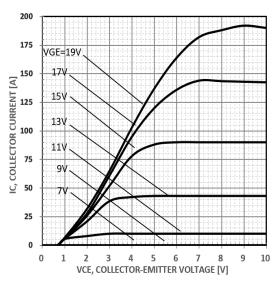


Figure 6. Typical output characteristics tp=300us Tc=150 $^{\circ}$ C

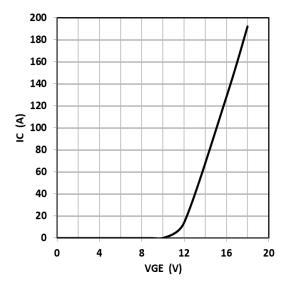


Figure 7. Typical gate threshold voltage

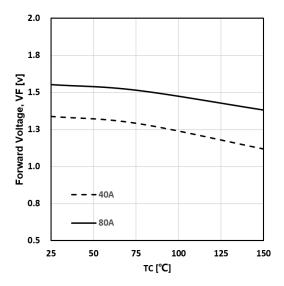


Figure 8. Typical forward voltage vs Tc





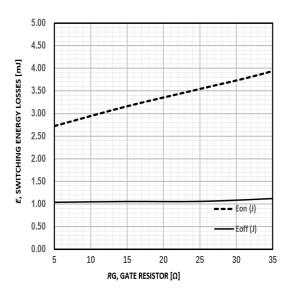


Figure9: Typical energy loss VS. Rg,TC=25°C, VCE=400V, VGE=15V ,IC=40A

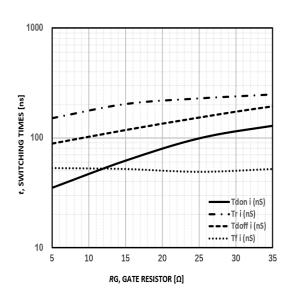


Figure 10: Typical switching time VS. Rg,TC=25°C, VCE=400V, VGE=15V ,IC=40A

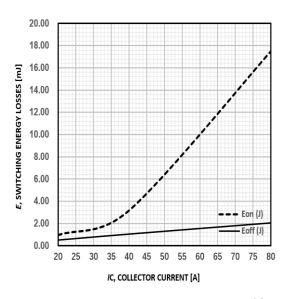


Figure11: Typical energy loss VS. IC, TC=25°C, $\label{eq:VCE=400V} VCE=400V, VGE=15V, RG=15\Omega$

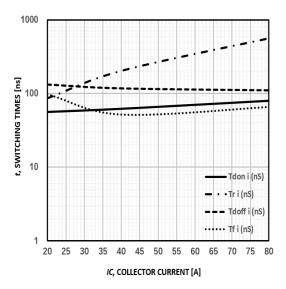


Figure 12: Typical switching time VS. IC, TC=25°C, VCE=400V, VGE=15V,RG=15 Ω



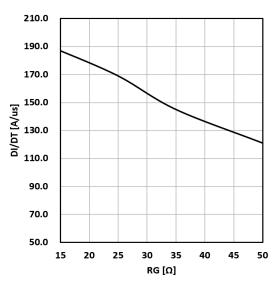


Figure 13. Typical diode di/dt vs rg Tc=25℃ VCE=400V VGE=15V IF=40A

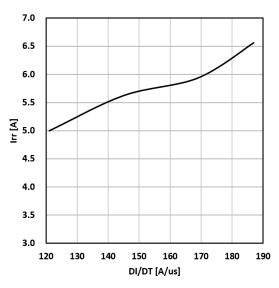


Figure 14. Typical diode irr vs di/dt Tc=25℃ VCE=400V VGE=15V IF=40A

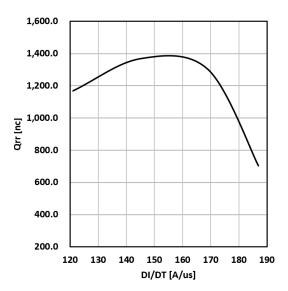


Figure 15. Typical diode Qrr vs di/dt $Tc=25^{\circ}C$ VCE=400V VGE=15V IF=40A

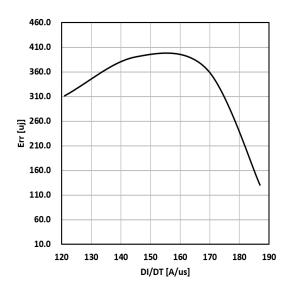


Figure 16. Typical diode Err vs di/dt Tc=25°C VCC=400V VGE=15V IF=40A



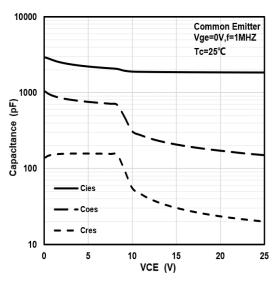


Figure17:Typical capacitance VS. VCE, VGE=0V,f=1MHz

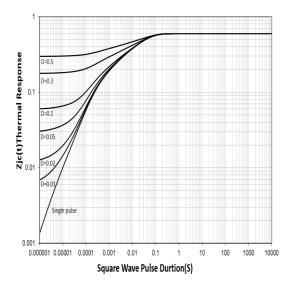
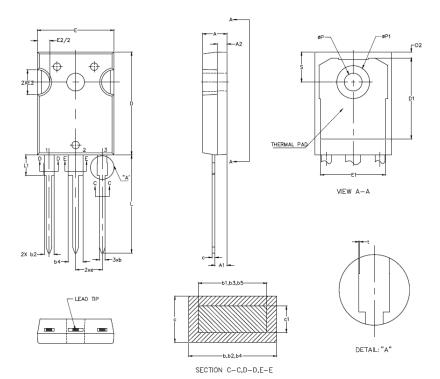


Figure 18. normalized transient thermal impedance, junction-to-case



Mechanical Dimensions



Ş X	DIMENSIONS					
B	mm		inch			
NY-MBOLIN	MIN.	MAX.	MIN.	MAX.		
Α	4.90	5.10	0.193	0.201		
A1	2.31	2.51	0.091	0.099		
A2	1.90	2.10	0.075	0.083		
Ь	1.16	1.26	0.046	0.050		
ь1	1.15	1.22	0.045	0.048		
b2	1.96	2.06	0.077	0.081		
b3	1.95	2.02	0.077	0.080		
b4	2.96	3.06	0.117	0.120		
b5	2.95	3.02	0.116	0.119		
С	0.59	0.66	0.023	0.026		
c1	0.58	0.62	0.023	0.024		
D	20.90	21.10	0.823	0.831		
D1	16.25	16.85	0.640	0.663		
D2	1.05	1.35	0.041	0.053		
Е	15.75	15.90	0.620	0.626		
E1	13.26		0.552	_		
E2	4.90	5.10	0.193	0.201		
е	5.44BSC		0.21	4BSC		
L	19.80	20.10	0.780	0.791		
L1		4.30		0.169		
øΡ	3.50	3.70	0.138	0.146		
øP1		7.40		0.291		
S	6.05	6.25	0.238	0.246		
t	0.00	0.15	0.000	0.006		



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